L	Hits	Search Text	DB	Time stamp
Number		AUCAF 15 10 HV DV	IICDAM.	2002/06/29
-	1	("6451512").PN.	USPAT; US-PGPUB	2003/06/28
	3	(("5563238") or ("3811931") or	USPAT;	2003/06/28
<del>-</del>	]	("3676401")).PN.	US-PGPUB	15:11
	1862	(resist or photoresist or photopolymer\$7)	USPAT;	2003/06/28
	1002	same (coupl\$3 or bond\$3 or prim\$3 or	US-PGPUB;	15:29
		adhes\$7) with (lactic or ketone or	EPO; JPO;	13,00
		organometal\$3 or metal adj salt or	IBM TDB	
		siloxane or silane or		
		hexamethyldisilazane or HMDS)		
-	1101	((resist or photoresist or	USPAT;	2003/06/28
		photopolymer\$7) same (coupl\$3 or bond\$3	US-PGPUB;	15:46
		or prim\$3 or adhes\$7) with (lactic or	EPO; JPO;	
		ketone or organometal\$3 or metal adj salt	IBM_TDB	
		or siloxane or silane or	_	
		hexamethyldisilazane or HMDS)) and		
		(semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3	ļ,	
		or bond\$3 or prim\$3 or adhes\$7)		2002/05/00
-	397		USPAT;	2003/06/28
		photopolymer\$7) same (coupl\$3 or bond\$3	US-PGPUB; EPO; JPO;	15:47
	i	or prim\$3 or adhes\$7) with (lactic or ketone or organometal\$3 or metal adj salt	IBM TDB	
		or siloxane or silane or	1511-155	
		hexamethyldisilazane or HMDS)) and		
		(semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3		
		or bond\$3 or prim\$3 or adhes\$7)) and		
		(degrad\$4 or decompos\$5 or break\$3 or		
		downgrad\$4 or deteriorat\$4 or		
		disintegrat\$4 or decay\$3 or dissolv\$4 or		
]		fragment\$4) same (coupl\$3 or bond\$3 or		
		prim\$3 or adhes\$7)		
-	42	((((resist or photoresist or	USPAT;	2003/06/28
		photopolymer\$7) same (coupl\$3 or bond\$3	US-PGPUB;	15:50
		or prim\$3 or adhes\$7) with (lactic or	EPO; JPO;	
		ketone or organometal\$3 or metal adj salt	IBM_TDB	
		or siloxane or silane or		
		hexamethyldisilazane or HMDS)) and (semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3		
		or bond\$3 or prim\$3 or adhes\$7)) and		
		(degrad\$4 or decompos\$5 or break\$3 or		
		downgrad\$4 or deteriorat\$4 or		
		disintegrat\$4 or decay\$3 or dissolv\$4 or		
		fragment\$4) same (coupl\$3 or bond\$3 or		
		prim\$3 or adhes\$7)) and		
		(430/311,319,327-329).ccls.		

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			HCDATT.	2002/07/00
-	355	((((resist or photoresist or	USPAT; US-PGPUB;	2003/07/09 12:01
		photopolymer\$7) same (coupl\$3 or bond\$3	EPO; JPO;	12.01
		or prim\$3 or adhes\$7) with (lactic or ketone or organometal\$3 or metal adj salt	IBM TDB	
		or siloxane or silane or	1011_100	
		hexamethyldisilazane or HMDS)) and		
		(semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3		
		or bond\$3 or prim\$3 or adhes\$7)) and		
		(degrad\$4 or decompos\$5 or break\$3 or		
		downgrad\$4 or deteriorat\$4 or		
		disintegrat\$4 or decay\$3 or dissolv\$4 or		
		fragment\$4) same (coupl\$3 or bond\$3 or		
		prim\$3 or adhes\$7)) not ((((resist or		
		photoresist or photopolymer\$7) same		
		(coupl\$3 or bond\$3 or prim\$3 or adhes\$7)		
		with (lactic or ketone or organometal\$3		
		or metal adj salt or siloxane or silane		
		or hexamethyldisilazane or HMDS)) and		
		(semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3		
	]	or bond\$3 or prim\$3 or adhes\$7)) and		
1		(degrad\$4 or decompos\$5 or break\$3 or		
		downgrad\$4 or deteriorat\$4 or		
		disintegrat\$4 or decay\$3 or dissolv\$4 or		
1		fragment\$4) same (coupl\$3 or bond\$3 or		
1		prim\$3 or adhes\$7)) and		
1_	0	(430/311,319,327-329).ccls.) ((light) near3 (degrad\$4) near3 (prim\$3	USPAT;	2003/07/09
-		or adhes\$7) same (resist or photoresist))	US-PGPUB;	12:39
		not (((resist or photoresist or	EPO; JPO;	12.05
		photopolymer\$7) same (coupl\$3 or bond\$3	IBM TDB	
1		or prim\$3 or adhes\$7) with (lactic or		
		ketone or organometal\$3 or metal adj salt		
		or siloxane or silane or		
		hexamethyldisilazane or HMDS)) and		
		(semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3		
		or bond\$3 or prim\$3 or adhes\$7)) and		
		(degrad\$4 or decompos\$5 or break\$3 or		
		downgrad\$4 or deteriorat\$4 or		
		disintegrat\$4 or decay\$3 or dissolv\$4 or		
		fragment\$4) same (coupl\$3 or bond\$3 or		
		<pre>prim\$3 or adhes\$7)) not (((((resist or photoresist or photopolymer\$7) same</pre>		
		(coupl\$3 or bond\$3 or prim\$3 or adhes\$7)		
		with (lactic or ketone or organometal\$3		
		or metal adj salt or siloxane or silane		
	1	or hexamethyldisilazane or HMDS)) and		
		(semiconduct\$3 or semi adj conduct\$3 or		
		wafer or silicon or "Si") same (coupl\$3		
		or bond\$3 or prim\$3 or adhes\$7)) and		
	1	(degrad\$4 or decompos\$5 or break\$3 or		
		downgrad\$4 or deteriorat\$4 or		
	ĺ	disintegrat\$4 or decay\$3 or dissolv\$4 or		
		fragment\$4) same (coupl\$3 or bond\$3 or		
		prim\$3 or adhes\$7)) and		
1	_	(430/311,319,327-329).ccls.)	IISDAT.	2003/07/09
-	l 0	((light) near3 (degrad\$4) near3 (prim\$3	USPAT; US-PGPUB;	12:40
		or adhes\$7) same (resist or photoresist))	EPO; JPO;	12.70
			IBM TDB	
l _	12	((light) near3 (degrad\$4) near3 (prim\$3	USPAT;	2003/07/16
1	1	or adhes\$7) and (resist or photoresist))	US-PGPUB;	16:26
1	1		EPO; JPO;	
	]		IBM TDB	
-	0		USPAT;	2003/07/09
	1	priming) same (resist or photoresist))	US-PGPUB;	12:47
	]		EPO; JPO;	
1	]		IBM_TDB	L
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-	88		USPAT;	2003/07/16
		near2 (resist or photoresist))	US-PGPUB;	16:27
			EPO; JPO;	
			IBM_TDB	
-	74	(((bilayer or bi adj layer) same positive	USPAT;	2003/07/18
•		near2 (resist or photoresist))) and	US-PGPUB;	13:13
		(thick or thickness) same (resist or	EPO; JPO;	
ļ		photoresist)	IBM TDB	
_	2	((hexamethyldisilazane or HMDS) near5	USPAT;	2003/07/18
		decompos\$4) same (resist or photoresist)	US-PGPUB;	14:06
		-	EPO; JPO;	
			IBM_TDB	
-	12	((hexamethyldisilazane or HMDS) near5	USPAT;	2003/07/18
		(light or uv)) same (resist or	US-PGPUB;	15:43
		photoresist)	EPO; JPO;	
			IBM_TDB	
_	92	(134/1.3).ccls. and (light or uv) same	USPAT;	2003/07/18
		(resist or photoresist)	US-PGPUB;	15:34
		· -	EPO; JPO;	
			IBM_TDB	
_	6	((134/1.3).ccls. and (light or uv) same	USPAT;	2003/07/18
		(resist or photoresist)) and	US-PGPUB;	15:35
		(hexamethyldisilazane or HMDS)	EPO; JPO;	:
			IBM_TDB	
_	17	((hexamethyldisilazane or HMDS) near5	USPAT;	2003/07/18
		(light or uv or ultraviolet)) same	US-PGPUB;	16:03
		(resist or photoresist)	EPO; JPO;	
	1		IBM_TDB	
-	16	, , = 2	USPAT;	2003/07/18
		((bond\$3 or coupl\$3) near2 (strength or	US-PGPUB;	16:17
		energy)) same ((silicon or Si) near5	EPO; JPO;	
		(oxygen))	IBM_TDB	
-	19		USPAT;	2003/07/18
		((bond\$3 or coupl\$3) near2 (strength or	US-PGPUB;	16:18
		energy)) same ("SiO" or "OSi")	EPO; JPO;	
			IBM TDB	